

TRENCHSTOP™ RC-Series for hard switching applications

IGBT with integrated diode in packages offering space saving advantage

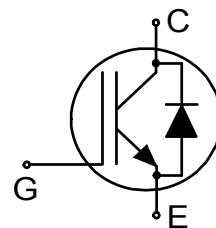
Features:

TRENCHSTOP™ Reverse Conducting (RC) technology for 600V applications offering

- Optimised V_{CEsat} and V_F for low conduction losses
- Smooth switching performance leading to low EMI levels
- Very tight parameter distribution
- Operating range of 1 to 20kHz
- Maximum junction temperature 175°C
- Short circuit capability of 5μs
- Best in class current versus package size performance
- Qualified according to JEDEC for target applications
- Pb-free lead plating; RoHS compliant (for PG-TO252: solder temperature 260°C, MSL1)
- Complete product spectrum and PSpice Models:
<http://www.infineon.com/igbt/>

Applications:

- Consumer motor drives

**Key Performance and Package Parameters**

| Type | V_{CE} | I_C | V_{CEsat} , $T_{vj}=25^\circ\text{C}$ | T_{vjmax} | Marking | Package |
|-----------|----------|-------|---|-------------|---------|------------|
| IKD06N60R | 600V | 6A | 1.65V | 175°C | K06R60 | PG-TO252-3 |

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Maximum Ratings

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

| Parameter | Symbol | Value | Unit |
|---|-------------|----------------|--------------------|
| Collector-emitter voltage, $T_{vj} \geq 25^{\circ}\text{C}$ | V_{CE} | 600 | V |
| DC collector current, limited by T_{vjmax} $T_c = 25^{\circ}\text{C}$ $T_c = 100^{\circ}\text{C}$ | I_C | 12.0 6.0 | A |
| Pulsed collector current, t_p limited by T_{vjmax} | I_{Cpuls} | 18.0 | A |
| Turn off safe operating area $V_{CE} \leq 600\text{V}$, $T_{vj} \leq 175^{\circ}\text{C}$, $t_p = 1\mu\text{s}$ | - | 18.0 | A |
| Diode forward current, limited by T_{vjmax} $T_c = 25^{\circ}\text{C}$ $T_c = 100^{\circ}\text{C}$ | I_F | 12.0 6.0 | A |
| Diode pulsed current, t_p limited by T_{vjmax} | I_{Fpuls} | 18.0 | A |
| Gate-emitter voltage | V_{GE} | ± 20 | V |
| Short circuit withstand time $V_{GE} = 15.0\text{V}$, $V_{CC} \leq 400\text{V}$ Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0\text{s}$ $T_{vj} = 150^{\circ}\text{C}$ | t_{SC} | 5 | μs |
| Power dissipation $T_c = 25^{\circ}\text{C}$ | P_{tot} | 100.0 | W |
| Operating junction temperature | T_{vj} | $-40\dots+175$ | $^{\circ}\text{C}$ |
| Storage temperature | T_{stg} | $-55\dots+150$ | $^{\circ}\text{C}$ |
| Soldering temperature, reflow soldering (MSL1 according to JEDEC J-STA-020) | | 260 | $^{\circ}\text{C}$ |

Thermal Resistance

| Parameter | Symbol | Conditions | Value | | | Unit |
|-----------|--------|------------|-------|------|------|------|
| | | | min. | typ. | max. | |

R_{th} Characteristics

| | | | | | | |
|---|---------------|--|---|---|------|-----|
| IGBT thermal resistance, ¹⁾ junction - case | $R_{th(j-c)}$ | | - | - | 1.50 | K/W |
| Diode thermal resistance, ²⁾ junction - case | $R_{th(j-c)}$ | | - | - | 3.60 | K/W |
| Thermal resistance, min. footprint junction - ambient | $R_{th(j-a)}$ | | - | - | 75 | K/W |
| Thermal resistance, 6cm ² Cu on PCB junction - ambient | $R_{th(j-a)}$ | | - | - | 50 | K/W |

¹⁾ R_{th}/Z_{th} based on single cooling pulse. Please be aware that a correct R_{th} measurement of the IGBT, is not possible using a thermocouple.

²⁾ R_{th}/Z_{th} based on single cooling pulse. Please be aware that a correct R_{th} measurement of the Diode, is not possible using a thermocouple.